### Welcome to O-leading

O-Leading strives to be your one stop solution partner in EMS supply chain, including PCB design , PCB fabrication and PCB assembly (PCBA). We provide some of the most advanced PCB technology, including HDI PCBs, multilayer PCBs, Rigid-Flexible PCBs. We can support from quick turn prototype to medium & mass Production.

In general, our global customers are very impressed with our services:rapid response, competitive price and quality commitment.Providing more valuable technical service and overall solution is the way Oleading forward. Printed circuit board supplier

Looking to the future, O-leading will concentrate on the innovation and development of electronics manufacturing technology as always, and make persistent efforts on PCB & PCBA one-stop service to provide first-class services and create more value for our customers.

We are professional PCB manufacturer with more than ten years experiences . Products range-single, double side ,multi-layer PCB ,flexible PCB and MCPCB.We can provide fast prototype service – S/S in  $24 \, \text{hrs}$ ,  $4-8 \, \text{layers}$  in 48-96 working hrs production time.

COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED

Pack with colorless transparent bubble film ,25 PCS/ bag, put desiccant in flank, put humidity indicator card on top side

### **Product Description**

Layers: 2 Material: FR4

Finished Thickness: 1.57mm +/- 10% Outer Layer Copper Thickness: 1oz

Finish: ENIG (Au:2-5u")

Soldermask (Color): Both Sides, LPI (Black) Silkscreen (Color): Both Sides, White

#### **Electrical test**

FINISH: THIS BOARD SHALL BE IMMERSION GOLD PLATED ACCORDING TO IPC-6012. THICKNESS SHALL BE .050uM OVER 3-6uM NICKEL.

COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED, EXCEPT VIAS .500 FINISH OR SMALLER.

#### **Layer Key:**

========

\*.GM4: Board Outline \*.TXT: NC Drill File

\*.GTP: Top Paste

\*.GTO: Top Silkscreen

\*.GTS: Top Soldermask \*.GTL: Top Copper Layer \*.GBL: Bottom Copper Layer \*.GBS: Bottom Soldermask \*.GBO: Bottom Silkscreen \*.GBP: Bottom Paste

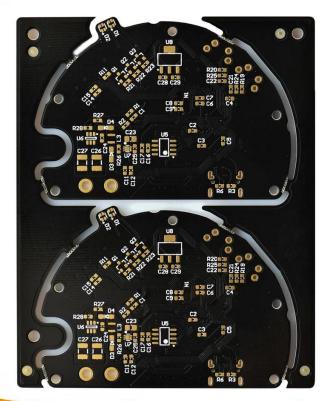












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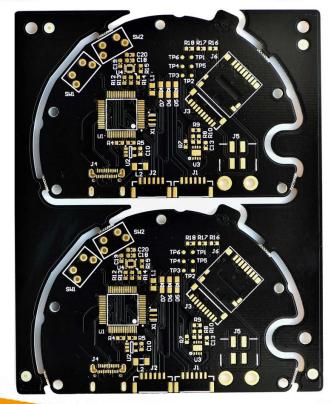












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High quality pcb wholesales

Our Team



### Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

### Factory SMT













## Certifications







Test Report

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

No. SZXEC1900530401

1313,FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

Date: 30 Mar 2019 Page 1 of 6

Test Report No. SZXEC1900530401 Date: 30 Mar 2019 Page 2 of 6

Test Results :

Test Part Description :

 Specimen No.
 SGS Sample ID
 Description

 SN1
 SZX19-005304.001
 Green\*PCB\*\*

(1) 1 mg/kg = 1 ppm = 0.0001% (2) MDL = Method Detection Limit

(3) ND = Not Detected ( < MDL )

(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC682321-5:2013, IEC62321-7:2:2017, IEC 62321-6:2015 and IEC62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s)	Limit	Unit	MDL	001
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	8
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (Cr(VI))	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg		ND
Monobromobiphenyl		mg/kg	5	ND
Dibromobiphenyl	12	mg/kg	5	ND
Tribromobiphenyl	10	mg/kg	5	ND
Tetrabromobiphenyl		mg/kg	5	ND
Pentabromobiphenyl		mg/kg	5	ND
Hexabromobiphenyl	E	mg/kg	5	ND
Heptabromobiphenyl		mg/kg	5	ND
Octabromobiphenyl		mg/kg	5	ND
Nonabromobiphenyl	- 4	mg/kg	5	ND
Decabromobiphenyl	æ	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether		mg/kg	5	ND
Dibromodiphenyl ether	14	mg/kg	5	ND
Tribromodiphenyl ether	2	mg/kg	5	ND
Tetrabromodiphenyl ether		mg/kg	5	ND
Pentabromodiphenyl ether		mg/kg	5	ND



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- Remark (14.0 post-times-days-scene)
(2586g to 4.1 post-times-form) (14.0 post-times-for

Member of the SGS Group (SGS SA)

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ Date of Sample Received : 22 Mar 2019

22 Mar 2019 - 30 Mar 2019 Testing Period :

Test Requested : Selected test(s) as requested by client. Test Method Please refer to next page(s).

Test Results : Please refer to next page(s).

Conclusion:

Based on the performed tests on submitted sample(s), the results of Lead. Mercury, Cadmium, Hexavalent chiromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBBcs) and Phthalates such as Bis(2-ethylbexyl) phthalate (DBFP). Bibutyl phthalate (DBFP). Tolbutyl phthalate (DBFP), and Diisobutyl phthalate (DBFP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/85/EU.

Signed for and on behalf of SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

lina

Tina Fan Approved Signatory



Max

Max

### UL Product iQ™



### ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

### Wiring, Printed - Component

See General Information for Wiring, Printed - Component

**Cond Width** 

#### O-LEADING SUPPLY CHAIN (HK) CO LTD

E490354

ROOM 1205, 12/F TAI SANG BANK BLDG 130-132 DES VOEUS ROAD CENTRAL, HONG KONG

		Min	Cond	SS/	Area	Solo	der	Oper		Meets	c
	Min	Edge	Thk	DS/	Diam	Lim	its	Temp	Flame	<b>UL796</b>	T
Type	mm(in)	mm(in)	mic(mil)	DSO	mm(in)	c	sec	c	Class	DSR	1
Multilayer (m	Multilayer (mass laminate) printed wiring boards.										
O-LEADING- 401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	3	153
O-LEADING- 407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer pri	nted wiring bo	ards.		50.							
O-LEADING- 408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
Single layer p	Single layer printed wiring boards.										
O-LEADING- 002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING- 003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	<b>A</b>	-
O-LEADING- 033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING- 205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING- 206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	
O-LEADING- D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
O-LEADING- S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

#### WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING- S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	НВ	<b>A</b>	*
O-LEADING- S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

 $<sup>\</sup>mbox{\ensuremath{\star}}$  - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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## Packaging & Delivery

## **Shipping service**











	Quick Turn Lead Time					
Layer Count:	Lead Tim	Special Requirement				
1L/2L	2-3days	24 Hours,48 Hours				
4L	3-4days	48 Hours				
6L	4-5days	72 Hours				
8L	5-6days	NA				
10L	6-7days	NA				
12L	7-8days	NA				
14L	8-9days	NA				

	Standard Lead Time					
Layer Count:	Sample Lead Time	Volume order lead time				
2L	4 days	10 days				
4L	5 days	11 days				
6L	6 days	12 days				
8L	8 days	14 days				
10L	10 days	16 days				
12L	12 days	18 days				
14L	14 days	20 days				
16-32L	18 days	24 days				

# Process Capability

### **SMT Production Capabilities**

PCB Material: FR-4,CEM-1,CEM-3,Aluminum-based board

Max PCB size: 510x460mm
Min PCB size[]50x50mm
PCB Thickness[]0.5mm-4.5mm
Board thickness[]0.5-4mm
Min Components size: 0201

Standard chip size component: 0603 and larger

Component max height ☐ 15mm

Min lead pitch: 0.3mm Min BGA ball pitch:0.4mm

Placement precision: +/-0.03mm